IN THE CLAIMS:

Please amend the claims to read as follows.

Claims 1-3 (Canceled).

Claim 4 (Currently Amended): A method of manufacturing a battery pack having a vessel, a battery mounted in the vessel and a circuit board connected to the battery, comprising:

a step of forming a terminal portion in manufacturing the circuit board, the step of forming the terminal portion including stacking a base layer of copper and a plated layer of gold successively to form the terminal portion,

wherein the circuit board is a square-shaped rigid-type printed wiring board made of glass epoxy resin;

a step of forming an insulating layer whose thickness is smaller than that of the terminal portion, after the step of forming the terminal portion in manufacturing the circuit board, the step of forming the insulating layer including forming the insulating layer in another area than an area where the terminal portion is formed,

wherein the insulating layer is formed so as to cover a peripheral edge of the plated layer by climbing up on the plated layer, so that the surface of the circuit board and at least one of the surface of the base layer are not exposed externally, and the insulating layer is made of epoxy resin; and

a step of mounting an electronic component after the step of forming the insulating layer, the step of mounting the electronic component including mounting the electronic component on given positions of the circuit board by a solder reflow process.

Claims 5-6 (Canceled).

Claim 7 (Currently Amended): A method of manufacturing a battery pack according to claim 4, wherein the step of forming the terminal portion further ~~comprising~~ comprises the steps of:

forming a base layer of a copper pattern on a surface of an insulating board;

forming a plated layer so as to cover the entire base layer by selective plating; and

forming the insulating layer on the plated layer and patterning the insulating layer so that only a portion of the plated layer is exposed externally.

Claims 8-10 (Canceled).

Claim 11 (Previously Presented): A method of manufacturing a battery pack according to claim 4, further comprising the step of:

stamping out a rigid-type integral board along each area thereof, on which the circuit board is to be formed, with a mold.

Claim 12 (Canceled).

Claim 13 (Currently Amended): A method of manufacturing a battery pack having a vessel, a battery mounted in the vessel and a circuit board connected to the battery, comprising:

a step of forming a terminal portion in manufacturing the circuit board, the step of forming the terminal portion including:

forming a base layer pattern on a surface of an insulating board;

forming a first plated layer so as to cover the entire base layer by selective plating; and

forming a second plated layer so as to cover the entire first plated layer by selective plating;

~~stacking a base layer of copper, a first plated layer of nickel, and a second plated layer of gold successively to form the terminal portion,~~

wherein the circuit board is a square-shaped rigid-type printed wiring board made of glass epoxy resin;

a step of forming an insulating layer whose thickness is smaller than that of the terminal portion, after the step of forming the terminal portion in manufacturing the circuit board, the step of forming the insulating layer including:

forming the insulating layer on the second plated layer; and patterning the insulating layer so that only a portion of the second plated layer is exposed externally,

~~forming the insulating layer in another area than an area where the terminal portion is formed,~~

wherein the insulating layer is formed so as to cover a peripheral edge of the second plated layer by climbing up on the plated layer, so that the surface of the circuit board and at least one of the surface of the base layer are not exposed externally, and the insulating layer is made of epoxy resin; and

~~further comprising the steps of:~~

~~forming the base layer pattern on a surface of an insulating board;~~

~~forming the first plated layer so as to cover the entire base layer by selective plating; and~~

~~forming the second plated layer so as to cover the entire first plated layer by selective plating; and~~

~~forming the insulating layer on the second plated layer and patterning the insulating layer so that only a portion of the second plated layer is exposed externally; and~~

a step of mounting an electronic component after the step of forming the insulating layer, the step of mounting the electronic component including mounting the electronic component on given positions of the circuit board by a solder reflow process.

Claim 14 (New): The method according to claim 4, wherein the thickness of the base layer of copper is about 35 μm.

Claim 15 (New): The method according to claim 4, wherein the thickness of the plated

layer of gold is about 1.5 μm.

Claim 16 (New): The method according to claim 4, wherein the step of forming the terminal portion further including: stacking a plated layer of nickel whose thickness is 4.0 μm or more.

Claim 17 (New): The method according to claim 4, wherein the thickness of the base layer of copper is about 35 μm, and the thickness of the plated layer of gold is about 1.5 μm.

Claim 18 (New): The method according to claim 4,

wherein the thickness of the base layer of copper is about 35 μm, and the thickness of the plated layer of gold is about 1.5 μm, and

wherein the step of forming the terminal portion further including: stacking a plated layer of nickel whose thickness is 4.0 μm or more.

Claim 19 (New): The method according to claim 4, further comprising:

a step of connecting the circuit board to the battery; and

a step of mounting the circuit board and the battery in the vessel.

Claim 20 (New): A method of manufacturing a battery pack having a vessel, a

battery mounted in the vessel and a circuit board connected to the battery, comprising:

a step of forming a terminal portion in manufacturing the circuit board, the step of forming the terminal portion including stacking a base layer of copper and a plated layer of gold successively to form the terminal portion,

wherein the circuit board is a square-shaped rigid-type printed wiring board made of glass epoxy resin;

a step of forming an insulating layer after the step of forming the terminal portion in manufacturing the circuit board, the step of forming the insulating layer including forming the insulating layer in another area than an area where the terminal portion is formed,

wherein the insulating layer is formed so as to cover a peripheral edge of the plated layer so that the surface of the circuit board and at least one of the surface of the base layer are not exposed externally, and the insulating layer is made of epoxy resin;

a step of mounting an electronic component after the step of forming the insulating layer, the step of mounting the electronic component including mounting the electronic component on given positions of the circuit board by a solder reflow process;

a step of connecting the circuit board to the battery; and

a step of mounting the circuit board and the battery in the vessel.